

EPIC European Photonics Industry Consortium

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Objective:

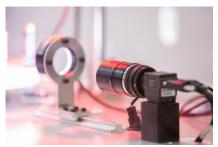
- 1. Support EPIC members for technology & business development
- 2. Help European companies access the markets outside Europe
- 3. Provide leading edge technology to system integrators / manufacturers worldwide.

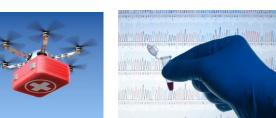
EPIC publishes market and technology reports, organizes technology workshops and B2B roundtables, coordinates EU funding proposals, advocacy and lobbying, education and training activities, standards and roadmaps, pavilions at exhibitions.

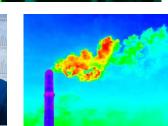
www.epic-assoc.com

Our members and activities encompass the entire value chain from:

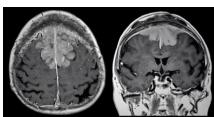
- Biophotonics
- Displays
- Imaging
- Lasers (for industrial, military, medical applications)
- LED, OLED, and Smart Lighting
- Optic fiber
- Optical components
- Photonic Integrated Circuits: III-V, Silicon Photonics, and TriPleX
- Projectors
- PV solar energy including CPV and OPV, and Batteries
- Sensors (for automotive, defense, medical, ... applications)
- and all other photonic related technologies













17-18 October

• EPIC Meeting on VCSEL Technology and Applications at Sony, Stuttgart, Germany

18 October

- EPIC Networking Lunch + Distributor Introductions at Laser World of Photonics, Mumbai, India

22-25 October

EPIC Delegation to Singapore

30-31 October

- EPIC Meeting on LIDAR for Automotive at Anteryon,
- Eindhoven, The Netherlands

7–8 November

 EPIC Meeting on Wafer Level Optics at SUSS Micro Optics, Neuchatel, Switzerland

19 November

 EPIC TechWatch on Medical Lasers at MEDICA, Dusseldorf, Germany

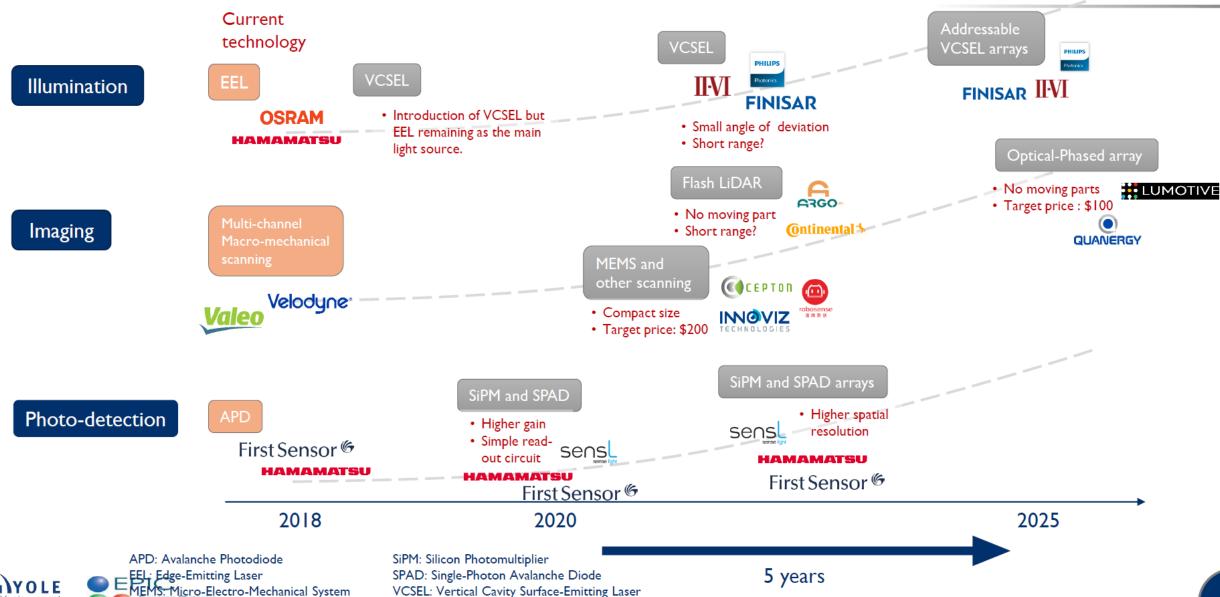
11-12 December

 EPIC Meeting on Photonics for Cancer Diagnostics and Treatment at NKI, Amsterdam, The Netherlands



TIME-TO-MARKET ANALYSIS

Introduction of new automotive LiDAR technologies







	Segment	Sensor application (light Rx)	Lighting application (light Tx)		
	Industry/space/ defense	Machine vision, barcode readers, professional & broadcast, defense, night vision camera	Datacom, 3D printing, AOC, Laser printer		
percent of the second of the s	Security	Security & surveillance cameras	Security & surveillance cameras		
	Medical	PET scan, x-ray, endoscopy	OCT systems, pulse oximeter, dermatology laser		
	Automotive	In-cabin, infotainment, front ADAS cameras, lidar	POF, lidar, eye tracking, Gesture recognition, automotive lighting		
	Computing	Laptop PC, tablets, computer mice	computer mice		
COUNTY	Consumer	DSLR, DSC, video cam, action cam, consumer drones, personal robotics, game stations, AR-VR headsets, smart home devices, smart watch	Laser printer, proximity sensors, autofocus systems, facial recognition, gas sensor, driver monitoring, gesture recognition		
YOLE OPPERENT OF PROTOICES	Mobile	Smartphones, feature phones	Smartphones, feature phones Status of CCM & WLO industry www.yole.fr ©2019		



AN INCREASING NUMBER OF PRODUCTS ARE REACHING THE MARKET*







From Technologies to Market

Special report on InP Wafer and Epiwafer - Photonics & RF

Technology, Industry and Market Trends for EPIC







DATA CENTERS - ARCHITECTURE AND DATA RATE InP DC: Data Center Inter DC: 100G & beyond (200G, 400G) DCI: Data Center Interconnect **DWDM** PSM4: parallel single-mode fiber Inter datacenter DCI Long Haul >600km (see appendix) DCI Metro 100km-600km CWDM4: Coarse wavelength division multiplexing (CWDM) (see DCI Edge 2km-100km Core appendix) Spine-Core: 40G - 100G & beyond (200G, 400G) Single-mode fiber **S**pine PSM4 or CWDM4 500m - 2 kmLeaf Optical transceivers (transmitter-receiver) with detachable connectors (Servers & storage) Top of the InP/GaAs rack (TOR) INTER-RACK: 40G, moving to 100G Multimode/singlemode fiber < 100m: active optical cable (AOC) with VCSELs 100 - 500m: InP Lowest-priced optical link AOC: transceivers with integrated fibers INTRA-RACK: 10G Direct attach cable (DAC) moving to 25G AOC I = 30 m

DAC: copper cables

Lowest-priced link

From Technologies to Market

Special report on Silicon Photonics and Photonic Integrated Circuits (PICs)

Technology, Industry and Market Trends for EPIC





THE DIFFERENT PIC PLATFORMS AND POSSIBLE FUNCTIONS

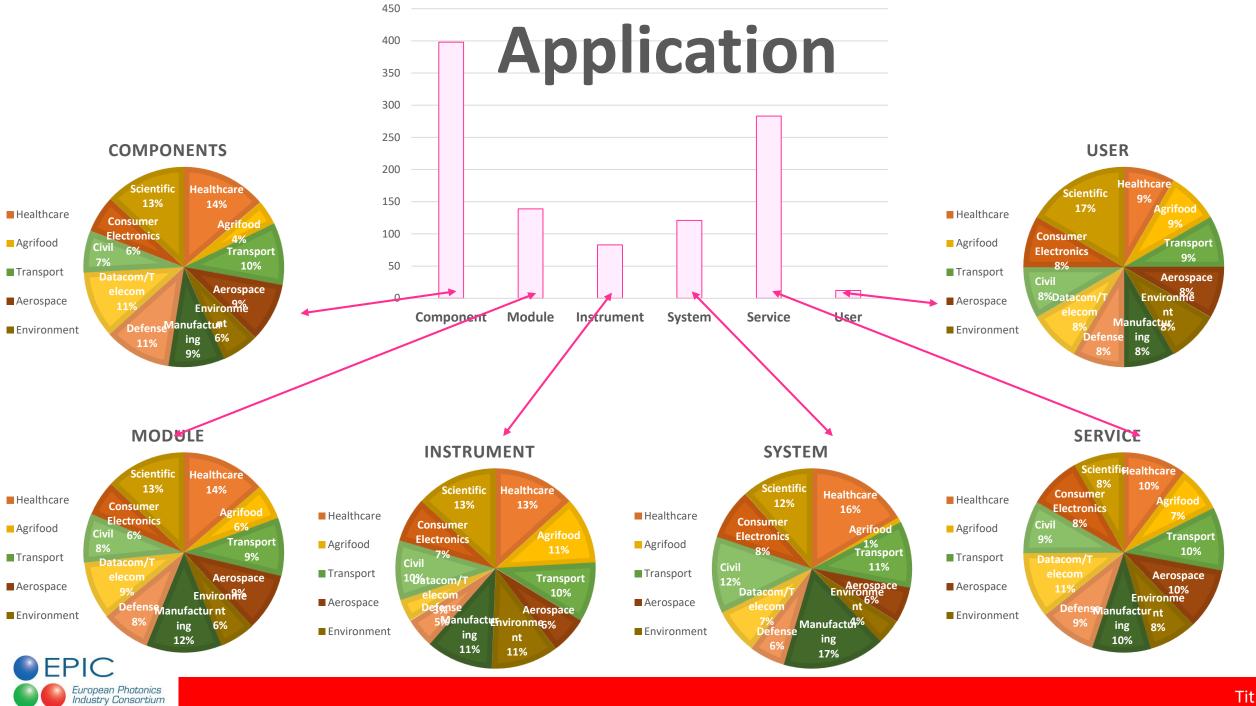


Table below shows which optical functions can be integrated into a PIC die (green).

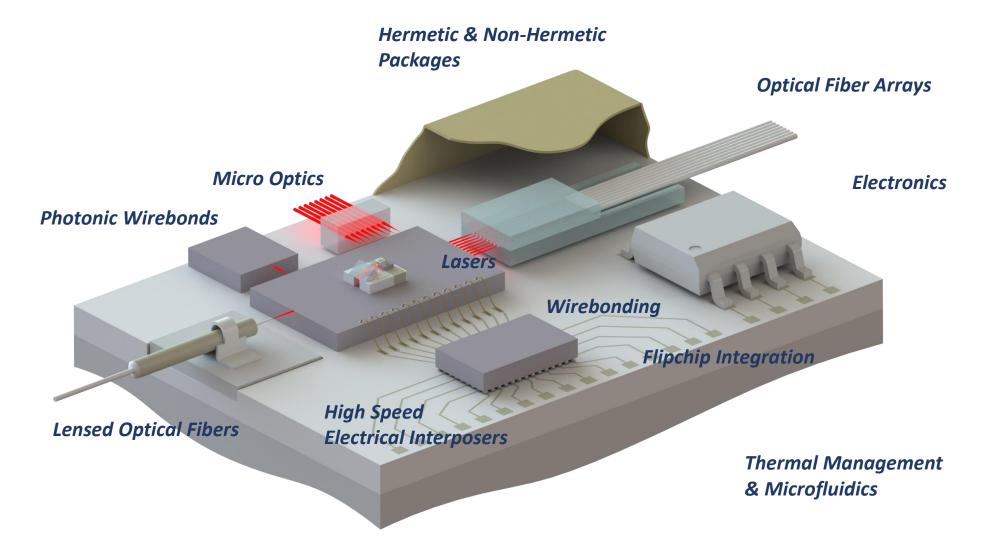
		SIGNAL MODULATION	EMISSION	AMPLIFIER	GUIDING	GUIDING	ELECTRONICS CONTROL	FILTERING	DETECTION	CONVERSION	ELECTRONICS CONTROL	COUPLING
PIC	Si photonics	SiPh die			SiPh die (SOI)	SiPh die (SOI)		SiPh die (SOI)	SiPh die (PN photodiode or PIN diode: Si or Ge)		SiPh die	
PIC	InP	EML: EAM + DFB/DBR	EML: EAM + DFB/DBR	PIN diode	WG							
PIC	InP	EML: EAM + DFB/DBR	EML: EAM + DFB/DBR	PIN diode	WG					EML w/ SOA		
PIC	InP		Laser			DWDM			APD			
PIC	SiN				Low loss WG							Coupler
PIC	Polymer	Modulator			WG	Mux/Demux						Spot converter
PIC	GaAs		VCSEL						PIN			
PIC	Silica				Splitters	AWG						
PIC	LiNbO3											
PIC	Glass				WG	splitters, taps, Mux/Demux, polarizers						Coupler







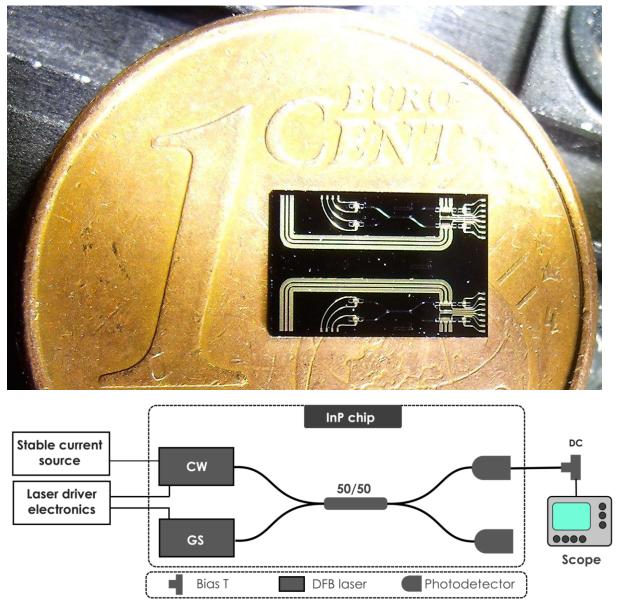
The Photonic Packaging Technologies



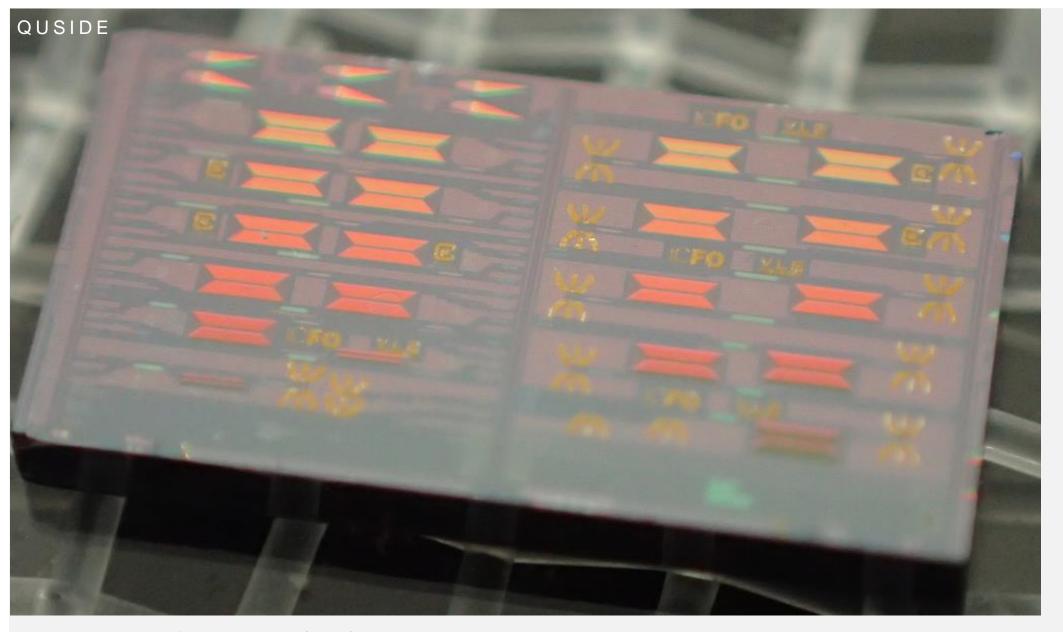




Fully integrated quantum entropy source



C. Abellan et al., *Optica* **3**, 9, 989–994 (2016)

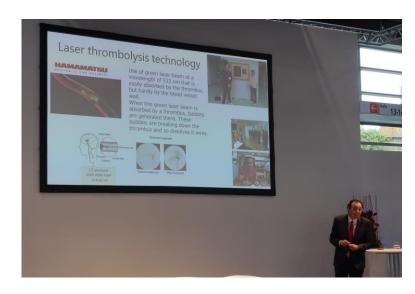


M. Rude et al., arXiv:1804.04482 (2018)



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500 members companies www.epic-assoc.com/membership/epic-members



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This presentation was presented at EPIC Meeting on VCSELs Technology and Applications 2019

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